

$V_{DS}=30V$

$R_{DS(ON)}, V_{GS}@10V, I_{DS}@45A=6m\Omega$

$R_{DS(ON)}, V_{GS}@4.5V, I_{DS}@30A=10m\Omega$

FEATURES

Advanced trench process technology

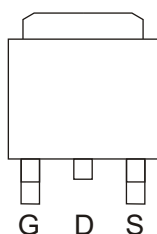
High Density Cell Design For Ultra Low On-Resistance

Specially Designed for DC/DC Converters and Motor Drivers

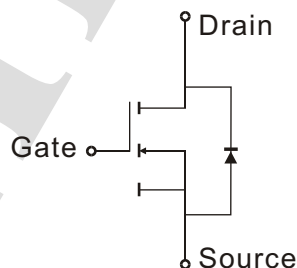
Fully Characterized Avalanche Voltage and Current

TO-252(D-PAK)

Top View



INTERNAL SCHEMATIC DIAGRAM



| Absolute Maximum Ratings ($T_A=25^{\circ}C$ Unless Otherwise Noted) | | | | |
|--|-----------------|--------------------|---------------|---|
| Parameter | Symbol | Limit | Unit | |
| Drain-Source Voltage | V_{DS} | 30 | V | |
| Gate-Source Voltage | V_{GS} | ± 20 | | |
| Continuous Drain Current | I_D | 60 | A | |
| Pulsed Drain Current ¹⁾ | I_{DM} | 350 | | |
| Maximum Power Dissipation | P_D | $T_A=25^{\circ}C$ | 70 | W |
| | | $T_A=100^{\circ}C$ | 42 | |
| Operating Junction Temperature | T_J | -55 to 150 | $^{\circ}C$ | |
| Storage Temperature Range | T_{stg} | | | |
| Avalanche Energy with Single Pulse $I_D = 50A, V_{DD} = 25V, L = 0.5mH$ | E_{AS} | 300 | mJ | |
| Junction-to-Case Thermal Resistance | $R_{\theta JC}$ | 1.8 | $^{\circ}C/W$ | |
| Junction-to-Ambient Thermal Resistance (PCB mounted) ²⁾ | $R_{\theta JA}$ | 40 | | |

Note: 1. Maximum DC current limited by the package
2. 1-in² 2oz Cu PCB board

30V N-Channel Enhancement Mode MOSFET

Electrical Characteristics (T_J = 25°C Unless Specified)

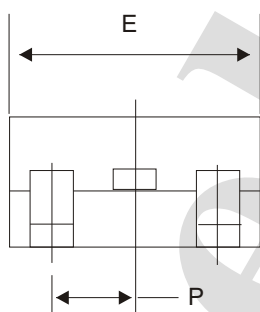
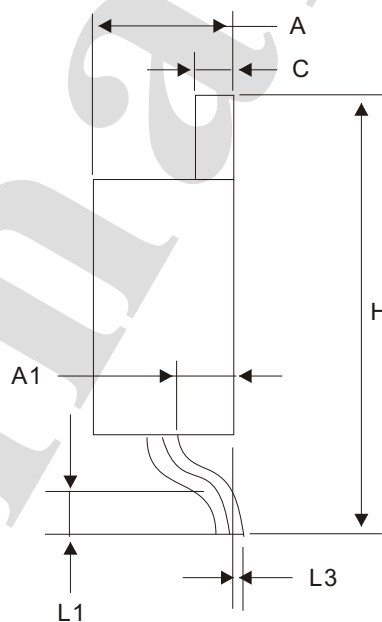
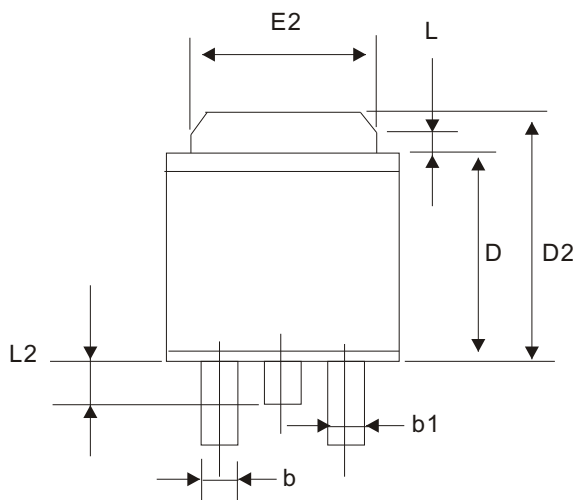
| Symbol | Parameter | Test Conditions | Min | Typ | Max | Unit |
|---------------------------|----------------------------------|---|-----|------|------|------|
| STATIC | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} = 0V, I _D = 250 μA | 25 | - | - | V |
| R _{DS(ON)} | Drain-Source On-State Resistance | V _{GS} = 4.5V, I _D = 30A | | 7.5 | 9.0 | mΩ |
| | | V _{GS} = 10V, I _D = 30A | | 4.5 | 6.0 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D = 250 μA | 1 | 1.6 | 3 | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 25V, V _{GS} = 0V | | | 1 | μA |
| I _{GSS} | Gate-Body Leakage | V _{GS} = ±20V, V _{DS} = 0V | | | ±100 | nA |
| R _g | Gate Resistance | | | 1 | | Ω |
| g _{fs} | Forward Transconductance | V _{DS} = 15V, I _D = 15A | | | | S |
| DYNAMIC | | | | | | |
| Q _g | Total Gate Charge | | | 26 | | nC |
| Q _{gs} | Gate-Source Charge | V _{DS} = 15V, I _D = 25A, V _{GS} = 10V | | 6 | | |
| Q _{gd} | Gate-Drain Charge | | | 5 | | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} = 15V, R _L = 15Ω I _D = 1A, V _{GEN} = 10V R _G = 6Ω | | 17 | | ns |
| t _r | Turn-On Rise Time | | | 3.5 | | |
| T _{d(off)} | Turn-Off Delay Time | | | 40 | | |
| t _f | Turn-Off Fall Time | | | 6 | | |
| C _{iss} | Input Capacitance | V _{DS} = 15V, V _{GS} = 0V f = 1.0 Mhz | | 2134 | | pF |
| C _{oss} | Output Capacitance | | | 343 | | |
| C _{rss} | Reverse Transfer Capacitance | | | 134 | | |
| SOURCE-DRAIN DIODE | | | | | | |
| I _s | Max. Diode Forward Current | | | | 20 | A |
| V _{sD} | Diode Forward Voltage | I _s = 20A, V _{GS} = 0V | | 0.85 | 1.2 | V |

Note: pulse test: pulse width ≤ 300us, duty cycle ≤ 2%

30V N-Channel Enhancement Mode MOSFET

Physical Dimensions inches(millimeters) unless otherwise noted

TO-252



| SYMBOL | MILLIMETERS | | INCHES | |
|--------|-------------|--------|--------|-------|
| | MIN | MAX | MIN | MAX |
| A | 2.250 | 2.350 | 0.089 | 0.093 |
| A1 | 0.950 | 1.050 | 0.037 | 0.041 |
| C | 0.490 | 0.530 | 0.019 | 0.021 |
| E | 6.400 | 6.600 | 0.252 | 0.260 |
| E2 | 5.300 | 5.450 | 0.209 | 0.215 |
| D | 6.000 | 6.200 | 0.236 | 0.244 |
| D2 | 7.100 | 7.300 | 0.280 | 0.287 |
| H | 9.700 | 10.100 | 0.382 | 0.398 |
| L | 0.600 | Ref | 0.024 | Ref |
| L1 | 1.425 | 1.625 | 0.056 | 0.064 |
| L2 | 0.650 | 0.850 | 0.026 | 0.033 |
| L3 | 0.020 | 0.120 | 0.001 | 0.005 |
| b | 0.770 | 0.850 | 0.030 | 0.033 |
| b1 | 0.840 | 0.940 | 0.033 | 0.037 |
| P | 2.290 | BSC | 0.090 | BSC |